HLMP-LD63, HLMP-LM63, HLMP-LB63

Precision Optical Performance Red, Green and Blue
New 4mm Standard Oval LEDs

AVAGO
TECHNOLOGIES

Data Sheet

Lead (Pb) Free
RoHS 6 fully
compliant

Description

These Precision Optical Performance Oval LEDs are specifically designed for full color/video and passenger information signs. The oval shaped radiation pattern and high luminous intensity ensure that these devices are excellent for wide field of view outdoor applications where a wide viewing angle and readability in sunlight are essential.

The package epoxy contains both UV-A and UV-B inhibitors to reduce the effects of long term exposure to direct sunlight.

Applications

- Full color signs

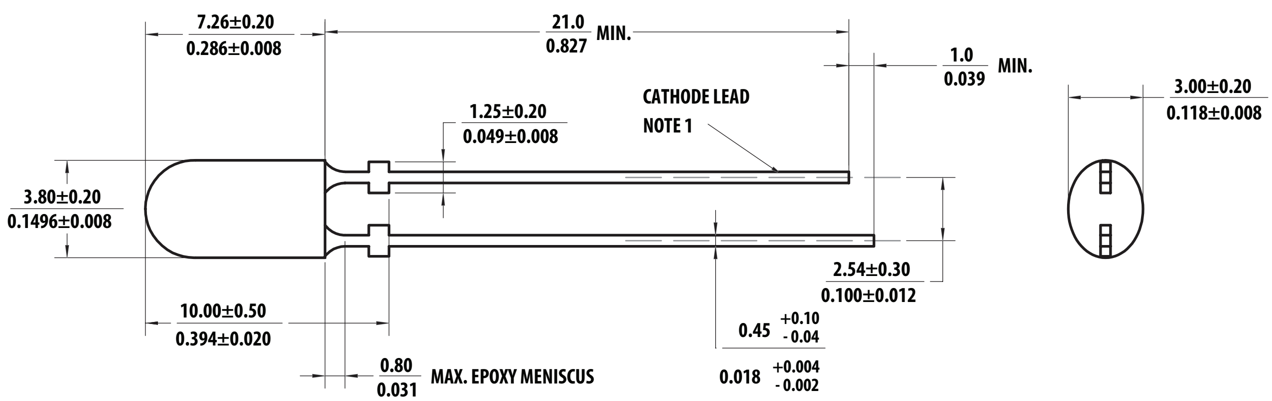
Features

- Well defined spatial radiation pattern
- High brightness material
- Available in red, green and blue color.

Red	AlInGaP	630nm
Green	InGaN	525nm
Blue	InGaN	470nm

- Superior resistance to moisture
- Standoff Package
- Typical viewing angle 50° x100°
- Tinted and diffused

Package Dimensions



Notes:
All dimensions in millimeters (inches).
Tolerance is ± 0.20mm unless other specified
For Blue and Green if heat sinking application is required, the terminal for heat sink is anode.

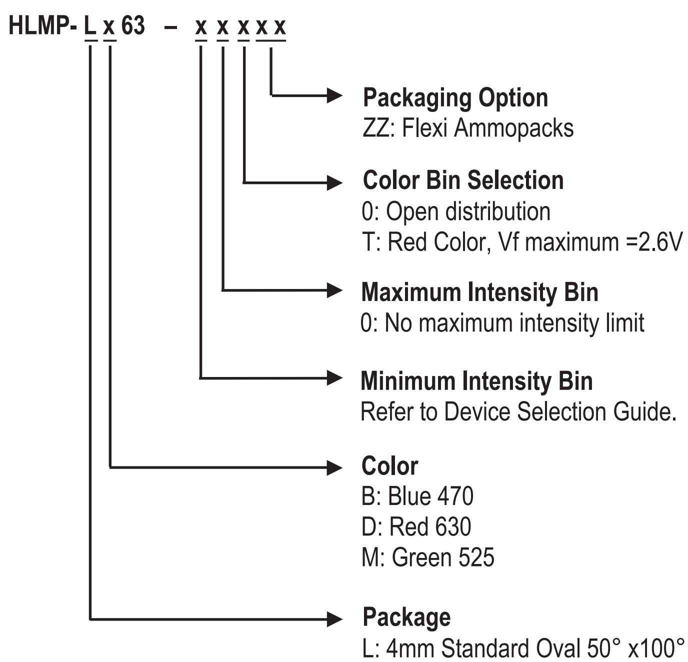
Caution: *InGaN devices are Class 1C HBM ESD sensitive per JEDEC Standard. Please observe appropriate precautions during handling and processing. Refer to Application Note AN-1142 for additional details.*

Device Selection Guide

Part Number	Color and Dominant Wavelength λd (nm) Typ	Luminous Intensity Iv (mcd) at 20 mA-Min	Luminous Intensity Iv (mcd) at 20 mA-Max
HLMP-LD63-SWTZZ	Red 630	660	1660
HLMP-LM63-X20ZZ	Green 525	1660	4200
HLMP-LB63-PT0ZZ	Blue 470	380	960

Tolerance for each intensity limit is ± 15%.
Notes:
1. The luminous intensity is measured on the mechanical axis of the lamp package.

Part Numbering System



Note: Please refer to AB 5337 for complete information about part numbering system.

Absolute Maximum Ratings, $T_A = 25°C$

Parameter	Red	Blue and Green	Unit
DC Forward Current [1]	50	30	mA
Peak Forward Current	100 [2]	100 [3, 4]	mA
Power Dissipation	130	111	mW
Reverse Voltage	5 (I_R = 100 µA)	5 (I_R = 10 µA)	V
LED Junction Temperature	130	110	°C
Operating Temperature Range	-40 to +100	-40 to +85	°C
Storage Temperature Range	-40 to +100	-40 to +100	°C

Notes:
1. Derate linearly as shown in Figure 2 and Figure 8.
2. Duty Factor 30%, frequency 1kHz.
3. Duty Factor 10%, frequency 1KHz.
4. For long term performance with minimal light output degradation, drive current below 15mA is recommended for Blue LED.

Electrical / Optical Characteristics, $T_A = 25°C$

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Forward Voltage						
Red		2.0	2.3	2.6 [1]		
Green	V_F	2.7	3.2	3.7	V	$I_F = 20$ mA
Blue		2.7	3.2	3.7		
Reverse Voltage						
Red	V_R	5			V	$I_R = 100\ \mu A$
Green & blue		5				$I_R = 10\ \mu A$
Dominant Wavelength [2]						
Red		622	630	634		
Green		520	525	540		$I_F = 20$ mA
Blue		460	470	480		
Peak Wavelength						
Red			639			Peak of Wavelength of Spectral
Green	λ_{PEAK}		516		nm	Distribution at $I_F = 20$ mA
Blue			464			
Thermal Resistance [3]	$R\theta_{J\text{-}PIN}$		240		°C/W	LED Junction-to pin
Luminous Efficacy [4]						
Red			155			Emitted Luminous Power/
Green	η_V		530		lm/W	Emitted
Blue			65			Radiant Power
Luminous Flux						
Red	φ_V		1300		mlm	$I_F = 20$ mA
Green			3700			
Blue			990			
Luminous Efficiency [5]						
Red	η_e		30		lm/W	Luminous Flux/Electrical Power
Green			60			$I_F = 20$ mA
Blue			16			

Notes:

1. For option –xxTxx, The V_F maximum is 2.6V, refer to VF bin table.
2. The dominant wavelength is derived from the chromaticity Diagram and represents the color of the lamp
3. For AlInGaP Red, thermal resistance applied to LED junction to cathode lead. For InGaN blue and green, thermal resistance applied to LED junction to anode lead.
4. The radiant intensity, Ie in watts per steradian, may be found from the equation $Ie = I_V/\eta_V$ where IV is the luminous intensity in candelas and η_V is the luminous efficacy in lumens/watt.
5. $\eta_e = \varphi_V / I_F \times V_F$, where φ_V is the emitted luminous flux, I_F is electrical forward current and V_F is the forward voltage.

AlInGaP Red

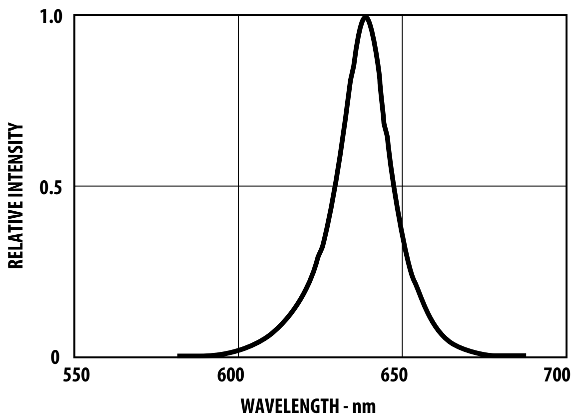


Figure 1. Relative Intensity vs Wavelength

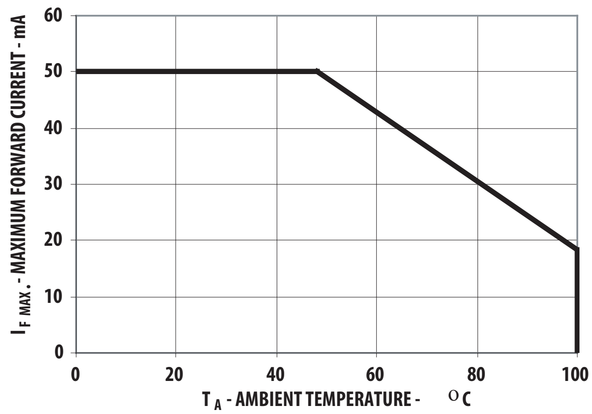


Figure 2. Maximum Forward Current vs Ambient Temperature

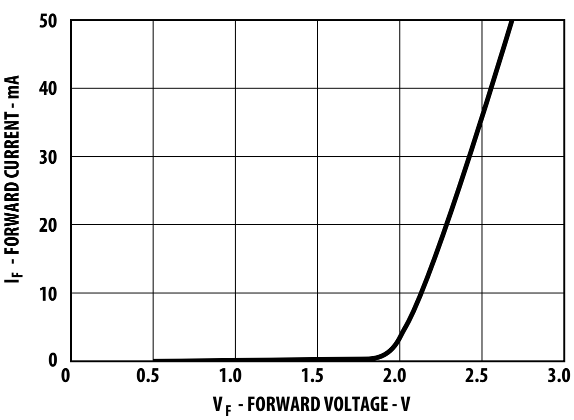


Figure 3. Forward Current vs Forward Voltage

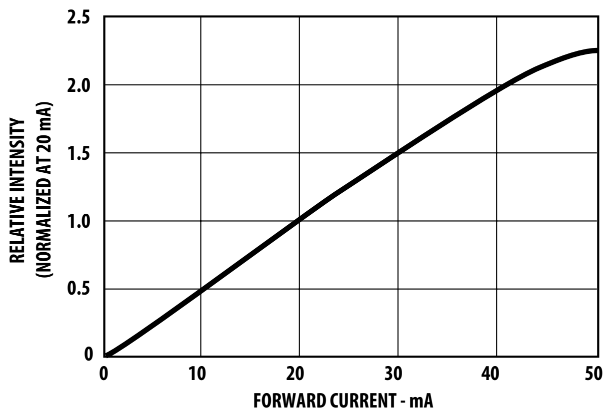


Figure 4. Relative Intensity vs Forward Current

InGaN Blue and Green

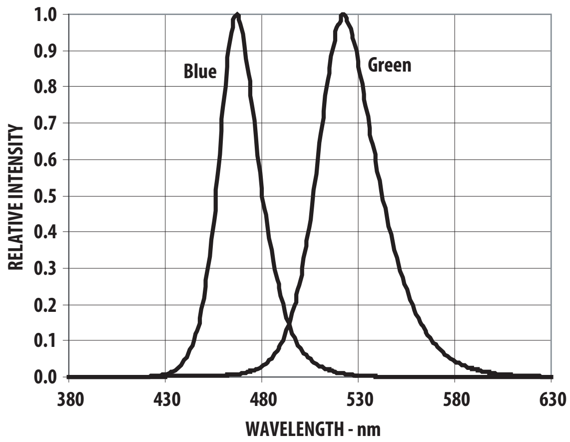


Figure 5. Relative Intensity vs Wavelength

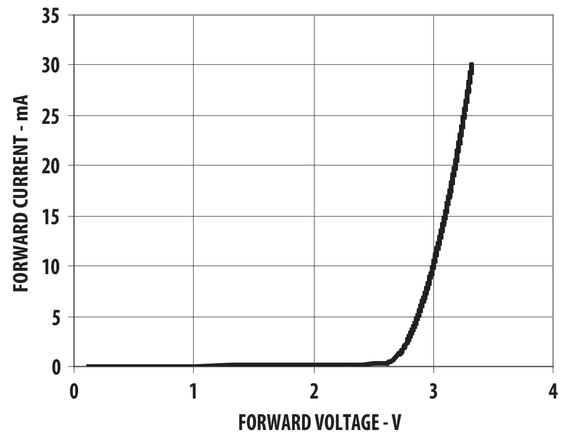


Figure 6. Forward Current vs Forward Voltage

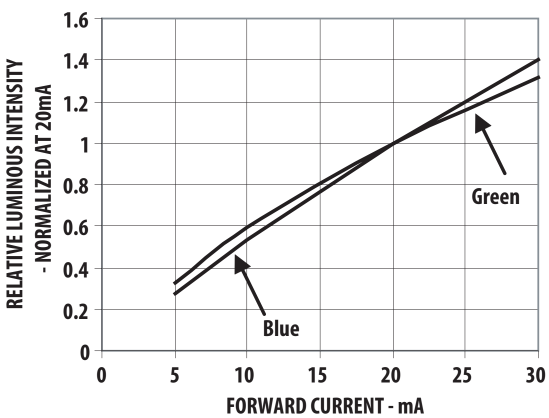


Figure 7. Relative Intensity vs Forward Current

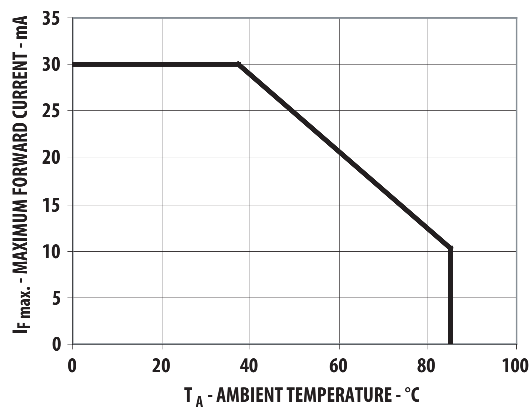


Figure 8. Maximum Forward Current vs Ambient Temperature

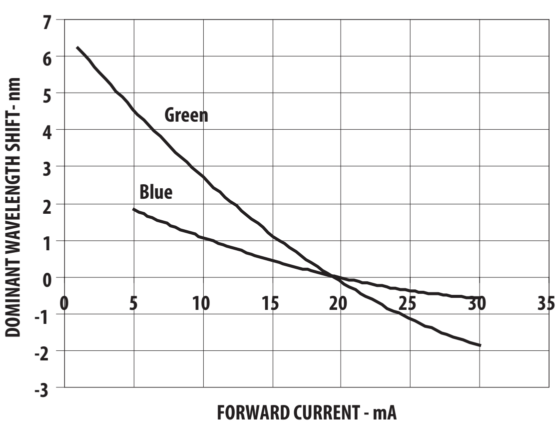


Figure 9. Relative dominant wavelength vs Forward Current

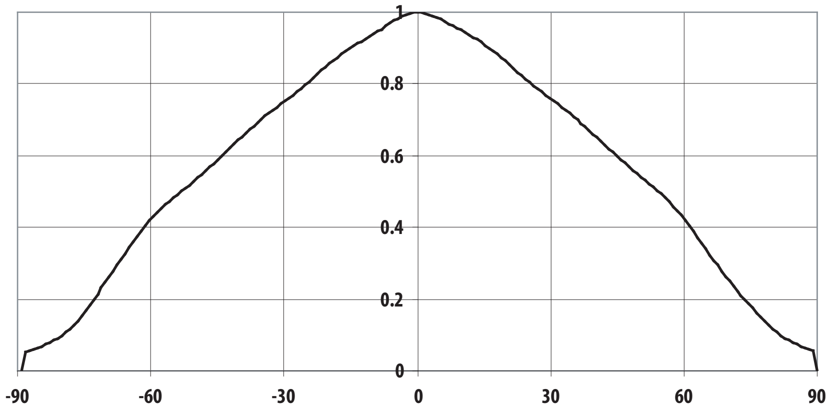


Figure 10. Radiation pattern-Major Axis

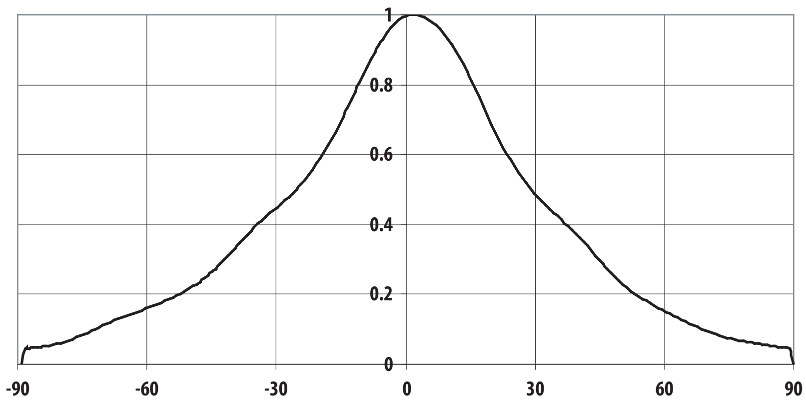


Figure 11. Radiation pattern-Minor Axis

Intensity Bin Limit Table (1.2: 1 Iv Bin Ratio)

	Intensity (mcd) at 20 mA	
Bin	**Min**	**Max**
P	380	460
Q	460	550
R	550	660
S	660	800
T	800	960
U	960	1150
V	1150	1380
W	1380	1660
X	1660	1990
Y	1990	2400
Z	2400	2900
1	2900	3500
2	3500	4200

Tolerance for each bin limit is ± 15%

VF Bin Table (V at 20mA)

Bin ID	Min	Max
VA	2.0	2.2
VB	2.2	2.4
VC	2.4	2.6

Tolerance for each bin limit is ± 0.05

Red Color Range

Min Dom	Max Dom	Xmin	Ymin	Xmax	Ymax
622	634	0.6904	0.3094	0.6945	0.2888
		0.6726	0.3106	0.7135	0.2865

Tolerance for each bin limit is ± 0.5nm.

Green Color Bin Table

Bin	Min Dom	Max Dom	Xmin	Ymin	Xmax	Ymax
1	520.0	524.0	0.0743	0.8338	0.1856	0.6556
			0.1650	0.6586	0.1060	0.8292
2	524.0	528.0	0.1060	0.8292	0.2068	0.6463
			0.1856	0.6556	0.1387	0.8148
3	528.0	532.0	0.1387	0.8148	0.2273	0.6344
			0.2068	0.6463	0.1702	0.7965
4	532.0	536.0	0.1702	0.7965	0.2469	0.6213
			0.2273	0.6344	0.2003	0.7764
5	536.0	540.0	0.2003	0.7764	0.2659	0.6070
			0.2469	0.6213	0.2296	0.7543

Tolerance for each bin limit is ± 0.5nm

Blue Color Bin Table

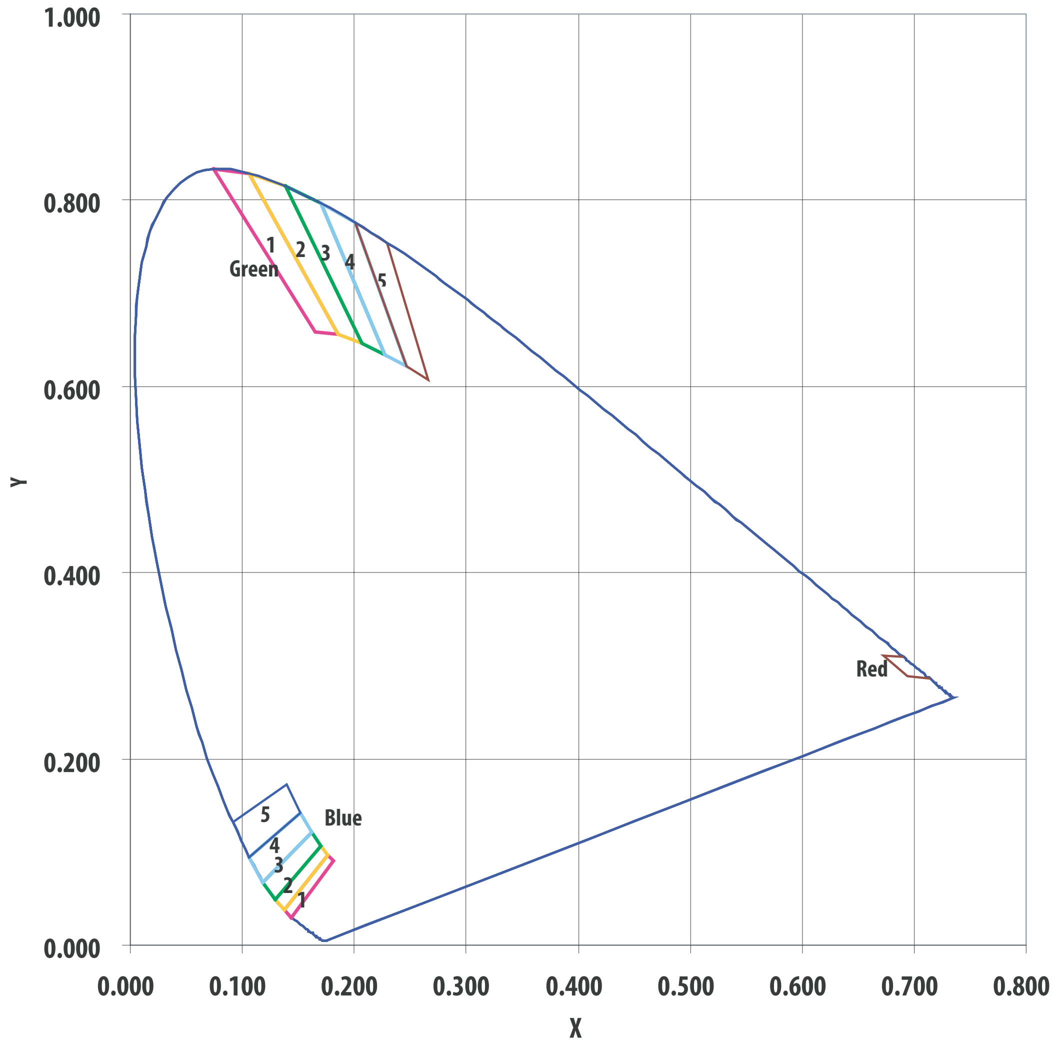
Bin	Min Dom	Max Dom	Xmin	Ymin	Xmax	Ymax
1	460.0	464.0	0.1440	0.0297	0.1766	0.0966
			0.1818	0.0904	0.1374	0.0374
2	464.0	468.0	0.1374	0.0374	0.1699	0.1062
			0.1766	0.0966	0.1291	0.0495
3	468.0	472.0	0.1291	0.0495	0.1616	0.1209
			0.1699	0.1062	0.1187	0.0671
4	472.0	476.0	0.1187	0.0671	0.1517	0.1423
			0.1616	0.1209	0.1063	0.0945
5	476.0	480.0	0.1063	0.0945	0.1397	0.1728
			0.1517	0.1423	0.0913	0.1327

Tolerance for each bin limit is ± 0.5nm

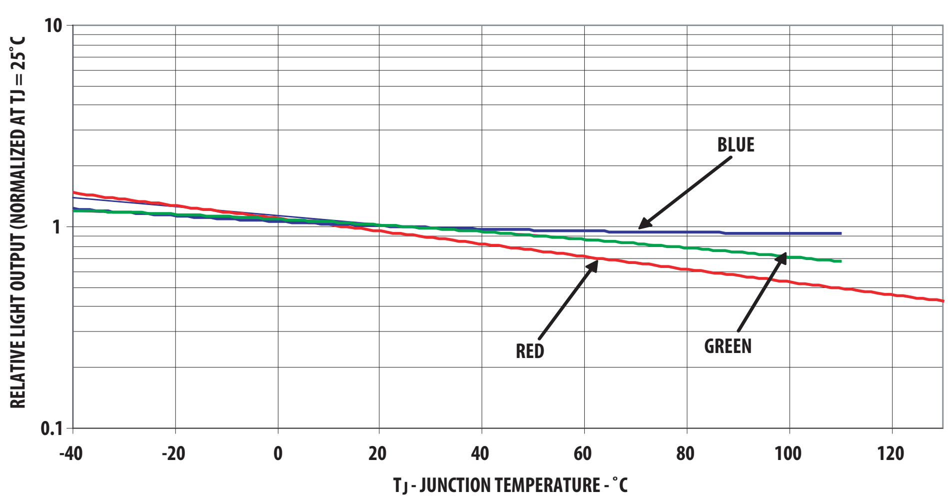
Note:

1. All bin categories are established for classification of products. Products may not be available in all bin categories. Please contact your Avago representative for further information.

Avago Color Bin on CIE 1931 Chromaticity Diagram



Relative Light Output vs Junction Temperature



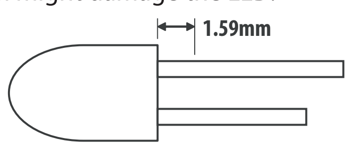
Precautions:

Lead Forming:

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering on PC board.
- For better control, it is recommended to use proper tool to precisely form and cut the leads to applicable length rather than doing it manually.
- If manual lead cutting is necessary, cut the leads after the soldering process. The solder connection forms a mechanical ground which prevents mechanical stress due to lead cutting from traveling into LED package. This is highly recommended for hand solder operation, as the excess lead length also acts as small heat sink.

Soldering and Handling:

- Care must be taken during PCB assembly and soldering process to prevent damage to the LED component.
- LED component may be effectively hand soldered to PCB. However, it is only recommended under unavoidable circumstances such as rework. The closest manual soldering distance of the soldering heat source (soldering iron's tip) to the body is 1.59mm. Soldering the LED using soldering iron tip closer than 1.59mm might damage the LED.



- ESD precaution must be properly applied on the soldering station and personnel to prevent ESD damage to the LED component that is ESD sensitive. Do refer to Avago application note AN 1142 for details. The soldering iron used should have grounded tip to ensure electrostatic charge is properly grounded.
- Recommended soldering condition:

	Wave Soldering [1, 2]	Manual Solder Dipping
Pre-heat temperature	105 °C Max.	-
Preheat time	60 sec Max	-
Peak temperature	250 °C Max.	260 °C Max.
Dwell time	3 sec Max.	5 sec Max

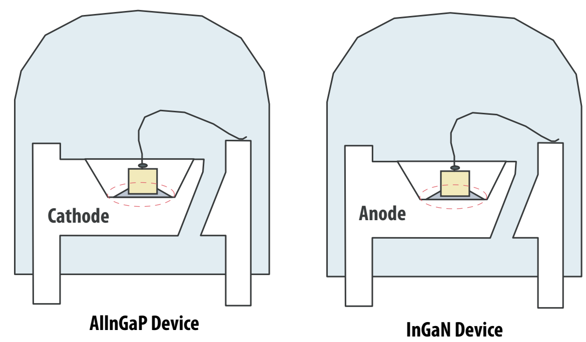
Note:
1. Above conditions refers to measurement with thermocouple mounted at the bottom of PCB.
2. It is recommended to use only bottom preheaters in order to reduce thermal stress experienced by LED.

- Wave soldering parameters must be set and maintained according to the recommended temperature and dwell time. Customer is advised to perform daily check on the soldering profile to ensure that it is always conforming to recommended soldering conditions.

Note:
1. PCB with different size and design (component density) will have different heat mass (heat capacity). This might cause a change in temperature experienced by the board if same wave soldering setting is used. So, it is recommended to re-calibrate the soldering profile again before loading a new type of PCB.
2. Avago Technologies' high brightness LED are using high efficiency LED die with single wire bond as shown below. Customer is advised to take extra precaution during wave soldering to ensure that the maximum wave temperature does not exceed 250°C and the solder contact time does not exceeding 3sec. Over-stressing the LED during soldering process might cause premature failure to the LED due to delamination.

Avago Technologies LED configuration

Note: Electrical connection between bottom surface of LED die and the lead frame is achieved through conductive paste.



- Any alignment fixture that is being applied during wave soldering should be loosely fitted and should not apply weight or force on LED. Non metal material is recommended as it will absorb less heat during wave soldering process.

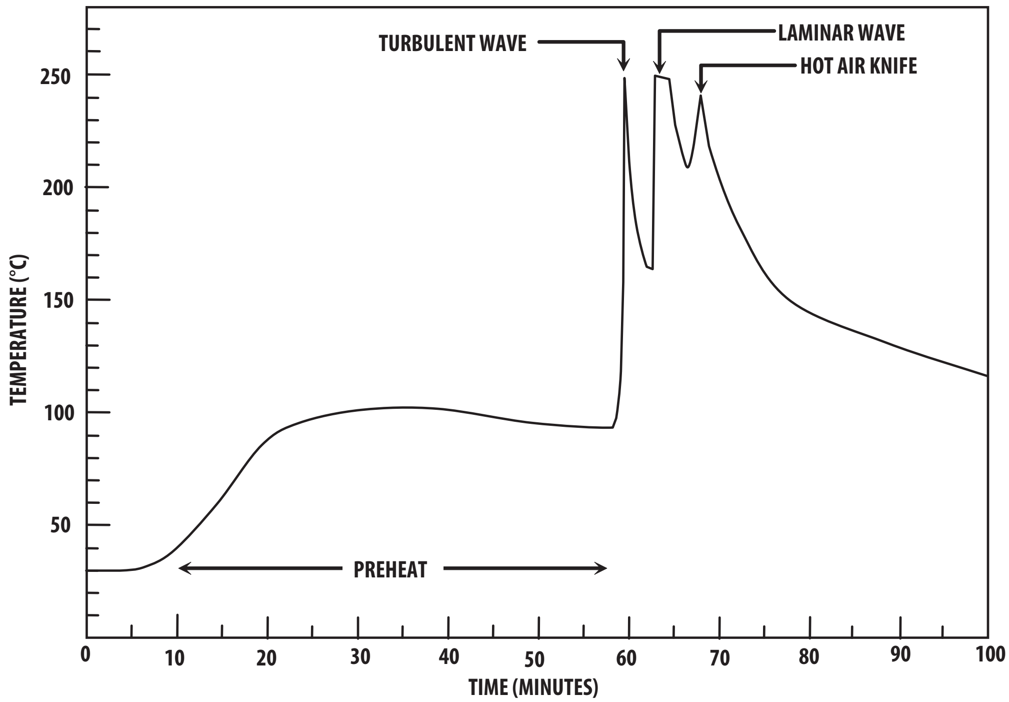
  Note: In order to further assist customer in designing jig accurately that fit Avago Technologies' product, 3D model of the product is available upon request.
- At elevated temperature, LED is more susceptible to mechanical stress. Therefore, PCB must allowed to cool down to room temperature prior to handling, which includes removal of alignment fixture or pallet.
- If PCB board contains both through hole (TH) LED and other surface mount components, it is recommended that surface mount components be soldered on the top side of the PCB. If surface mount need to be on the bottom side, these components should be soldered using reflow soldering prior to insertion the TH LED.
- Recommended PC board plated through holes (PTH) size for LED component leads.

LED component lead size	Diagonal	Plated through hole diameter
0.45 x 0.45 mm (0.018x 0.018 inch)	0.636 mm (0.025 inch)	0.98 to 1.08 mm (0.039 to 0.043 inch)
0.50 x 0.50 mm (0.020x 0.020 inch)	0.707 mm (0.028 inch)	1.05 to 1.15 mm (0.041 to 0.045 inch)

- Over-sizing the PTH can lead to twisted LED after clinching. On the other hand under sizing the PTH can cause difficulty inserting the TH LED

Refer to application note AN5334 for more information about soldering and handling of high brightness TH LED lamps.

Example of Wave Soldering Temperature Profile for TH LED



Recommended solder:
Sn63 (Leaded solder alloy)
SAC305 (Lead free solder alloy)

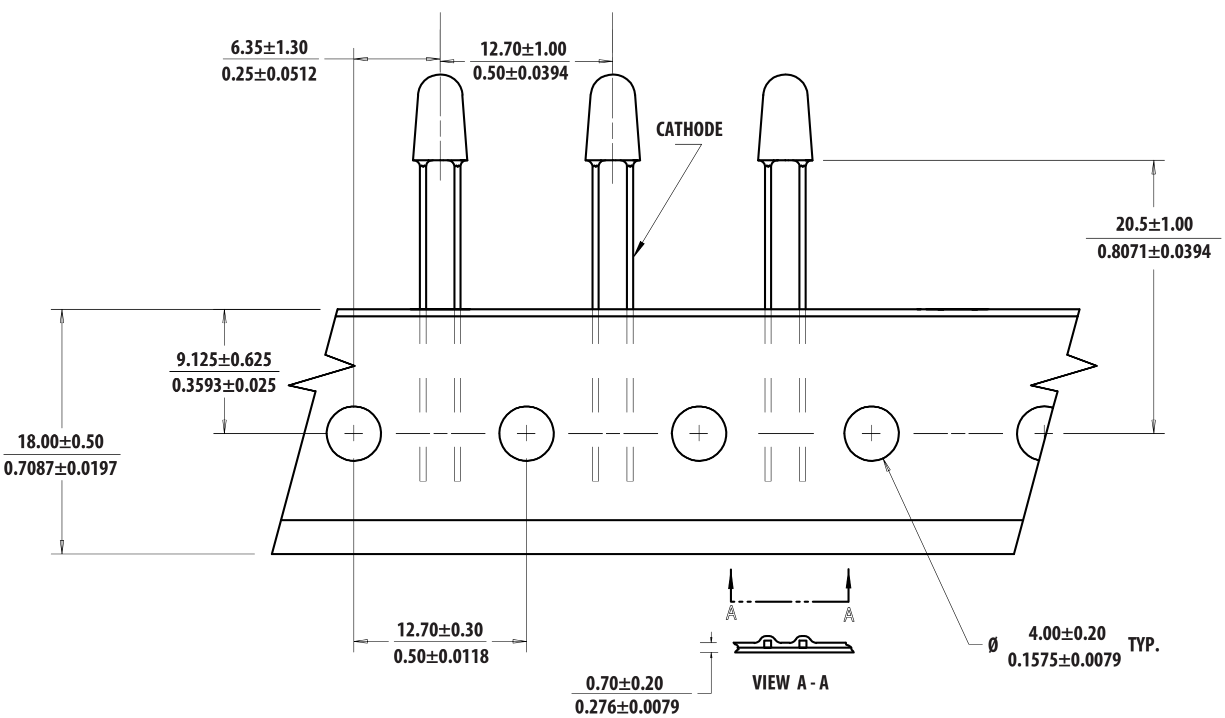
Flux: Rosin flux

Solder bath temperature:
245°C± 5°C (maximum peak temperature = 250°C)

Dwell time: 1.5 sec - 3.0 sec (maximum = 3sec)

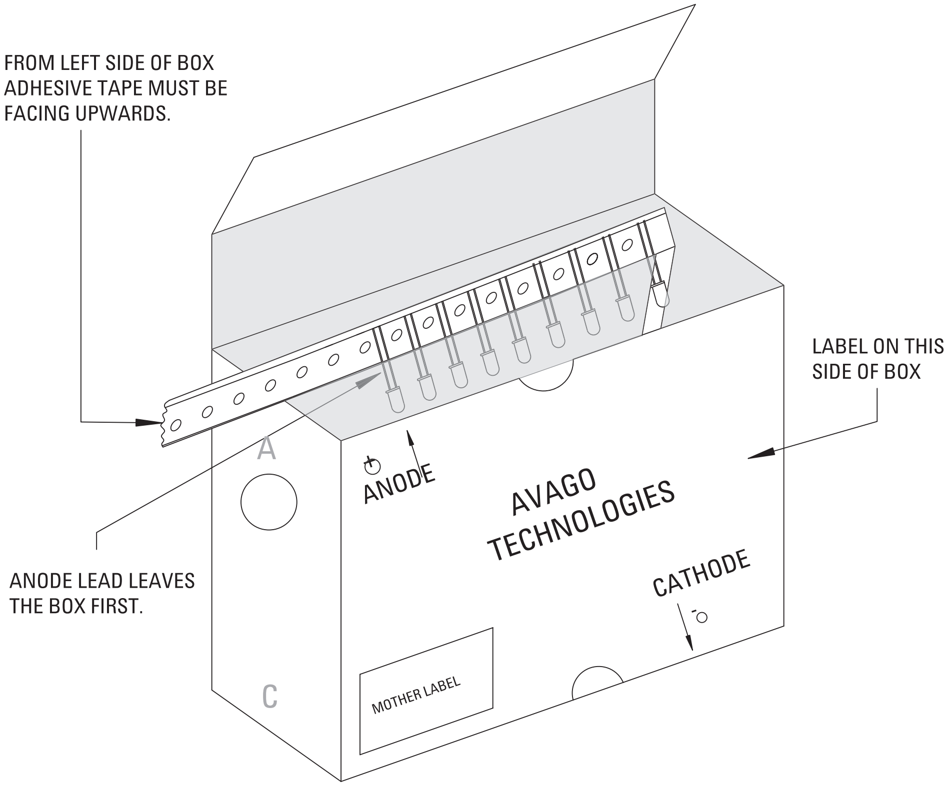
Note: Allow for board to be sufficiently cooled to room temperature before exerting mechanical force.

Ammo Packs Drawing



Note: The ammo-packs drawing is applicable for packaging option –DD & -ZZ and regardless standoff or non-standoff

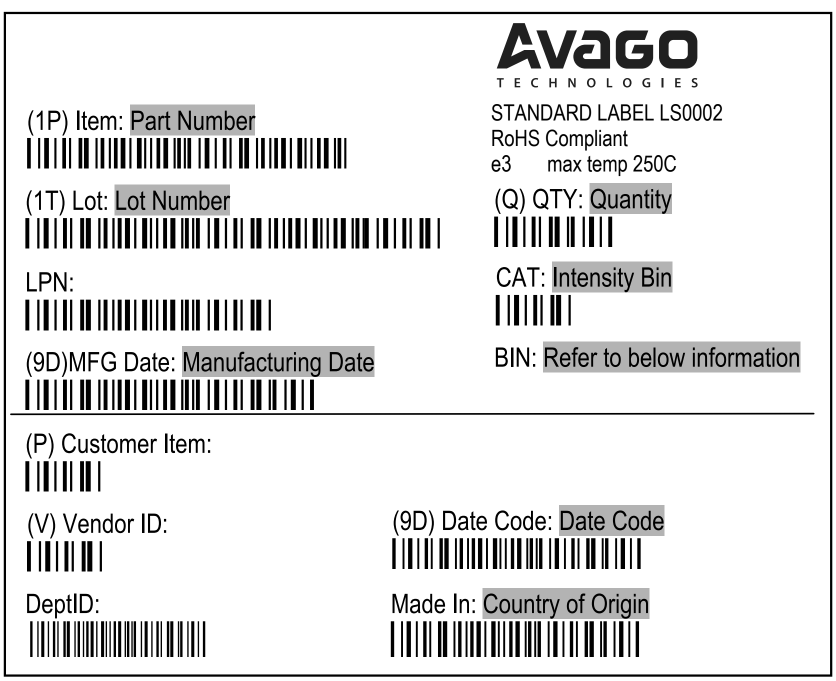
Packaging Box for Ammo Packs



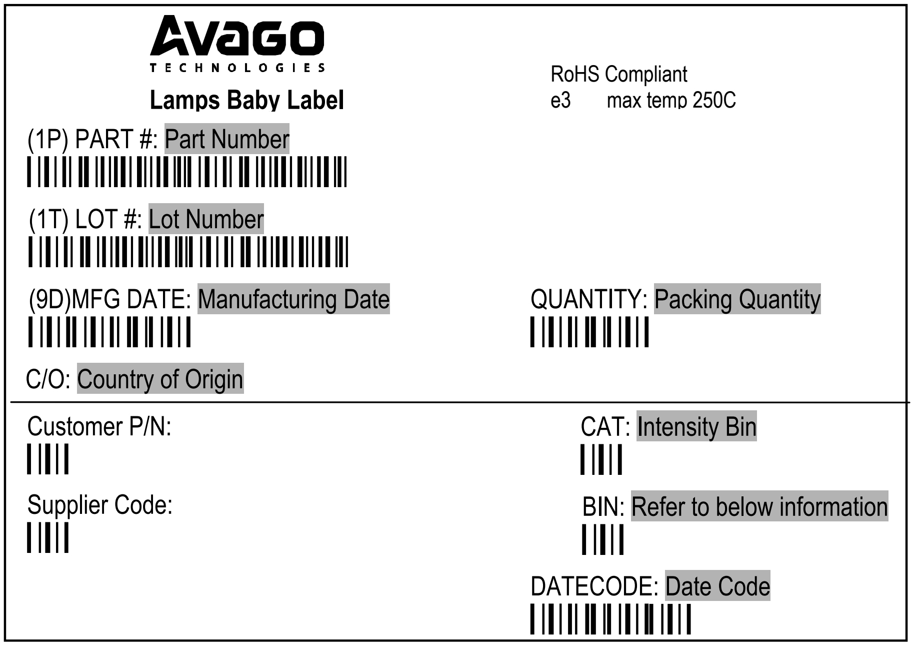
Note: For InGaN device, the ammo pack packaging box contain ESD logo

Packaging Label

(i) Avago Mother Label: (Available on packaging box of ammo pack and shipping box)



(ii) Avago Baby Label (Only available on bulk packaging)



Acronyms and Definition:

BIN:

(i) Color bin only or VF bin only

(Applicable for part number with color bins but without VF bin OR part number with VF bins and no color bin)

OR

(ii) Color bin incorporated with VF Bin

(Applicable for part number that have both color bin and VF bin)

Example:

(i) Color bin only or VF bin only

BIN: 2 (represent color bin 2 only)

BIN: VB (represent VF bin "VB" only)

(ii) Color bin incorporate with VF Bin

BIN: 2VB

→ VB: VF bin "VB"

→ 2: Color bin 2 only

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